

### MAIN CHARACTERISTICS

$I_D$	106A
$V_{DS}$	1200V
$R_{os(on)-Typ@ V_{gs}=18V}$	27m $\Omega$

### FEATURES

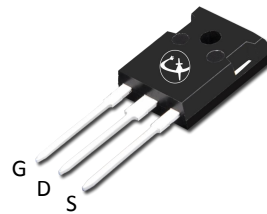
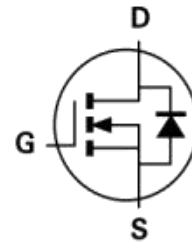
- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low RDS(on)
- Easy to Parallel
- Simple to Drive

### Benefits

- Increased Power Density
- Faster Operating Freequenc
- Reduction of Heat Sink Requirements
- Higher Efficiency
- Reduced EMI

### APPLICATIONS

- Power Factor Correction Modules
- Switch Mode Power Supplies
- DC-AC Inverters
- High Voltage DC/DC Converters



TO-247

### Product specification classification

Part Number	Package	Mode Name	Pack
LSC030M120B	TO-247	LSC030M120B	Tube

### Maximum Ratings at Tc=25°C unless otherwise specified

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	1200	V
Gate-Source Voltage	$V_{GS}$	-8/+22	V
Recommended Operation Value	VGSop	-4/+18	V
Continue Drain Current Tc=25°C	$I_D$	106	A
Continue Drain Current Tc=100°C		75	
Pulsed Drain Current	$I_{DM}$	210	A
Power Dissipation TC=25°C	$P_D$	517	W
Power Dissipation TC=100°C		258	
Operating Temperature Range	$T_J$	-40 to +175	°C
Storage Temperature Range	$T_{STG}$	-40 to +175	°C
Thermal Resistance, Junction to Case	$R_{\theta JC}$	0.29	°C/W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	26.8	°C/W

Note1:Pulse test: 300  $\mu$ s pulse width, 2 % duty cycle

### Electrical Characteristics at Tc=25°C unless otherwise specified

Parameter	Test Condition	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = 0 V, I_D = 100\mu A$	$BV_{DSS}$	1200	-	-	V
Drain-Source Leakage Current	$V_{DS} = 1200 V, V_{GS} = 0 V$	$I_{DSS}$	-	1	-	$\mu A$
Gate Leakage Current	$V_{GS} = 18 V, V_{DS} = 0 V$	$I_{GSS}$	-	-	250	nA
Gate-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 14 mA$	$V_{GS(th)}$	2	2.8	4	V
	$V_{DS} = V_{GS}, I_D = 14 mA$ $T_J = 175^\circ C$		-	2.1	-	V
Drain-Source On-State Resistance	$V_{GS} = 18 V, I_D = 50 A$	$R_{DS(on)}$	-	27	35	m $\Omega$
	$V_{GS} = 18 V, I_D = 50 A,$ $T_J = 175^\circ C$		-	40	-	m $\Omega$
Input Capacitance		$C_{iss}$	-	2990	-	pF
Output Capacitance	$V_{DS}=1000V, V_{GS}=0V,$ $f=100kHz$	$C_{oss}$	-	143	-	pF
Reverse Transfer Capacitance		$C_{rss}$	-	8.9	-	pF
Coss Stored Energy		$E_{oss}$	-	175	-	$\mu J$
Total Gate Charge(Note2)	$I_D = 50A, V_{DD} = 800V,$ $V_{GS} = -4/+ 18 V$	$Q_G$	-	134	-	nC
Gate to Source Charge(Note2)		$Q_{GS}$	-	32	-	nC
Gate to Drain Charge(Note2)		$Q_{GD}$	-	44	-	nC

### Electrical Characteristics at Tc=25°C unless otherwise specified

Turn-on Switching Energy	$V_{DS} = 800 V, I_D = 50A,$ $V_{GS} = -4/+18 V,$ $RG(int) = 2.5 \Omega L = 200\mu H$	Eon	-	283	-	$\mu J$
Turn-off Switching Energy		Eoff	-	95	-	$\mu J$
Turn-on Delay Time(Note2)		$t_{d(ON)}$	-	17	-	ns
Rise Time(Note2)		$t_r$	-	15	-	ns
Turn-Off Delay Time(Note2)		$t_{d(OFF)}$	-	28	-	ns
Fall Time(Note2)		$t_f$	-	8	-	ns

**Source-Drain Diode Characteristics at Ta=25°C unless otherwise specified**

Parameter	Test Condition	Symbol	Min.	Typ.	Max.	Unit
Maximun Body-Diode Continuous Current	VGS = -4 V, Tc=25°C	I <sub>S</sub>	-	105	-	A
	VGS = -4 V, Tc=100°C		-	59	-	A
Maximun Body-Diode Pulsed Current(Note2)		I <sub>SM</sub>	-	210	-	A
Drain-Source Diode Forward Voltage	VGS = -4 V, I <sub>SD</sub> = 25 A	V <sub>SD</sub>	-	3.8	-	V
	VGS = -4 V, I <sub>SD</sub> =25 A Tj=175°C		-	3.4	-	V
	VGS = -4 V, I <sub>SD</sub> = 50 A		-	4.3	-	V
	VGS = -4 V, I <sub>SD</sub> =50 A Tj=175°C		-	3.9	-	V
Reverse Recovery Time(Note2)	VGS = -4 V, I <sub>SD</sub> = 50 A,	trr	-	18	-	ns
Reverse Recovery Charge(Note2)	V <sub>R</sub> =800V, dIF/dt	Qrr	-	373	-	nC
Peak Reverse Recovery Current	=3692A/μs	Irrm	-	38	-	A

Note2:Pulse test: 300 μs pulse width, 2 % duty cycle

## RATINGS AND CHARACTERISTIC CURVES

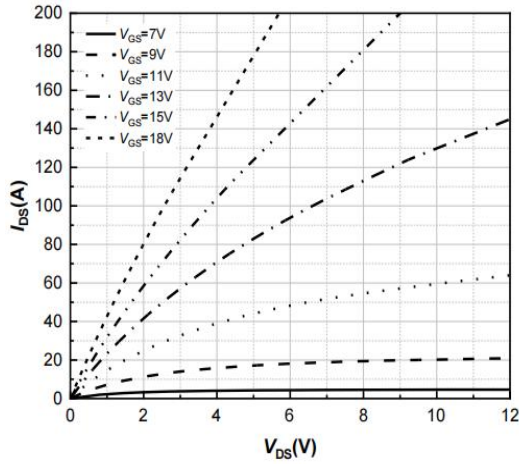


Figure 1. Output Characteristics  
 $T_j = -40^\circ\text{C}$

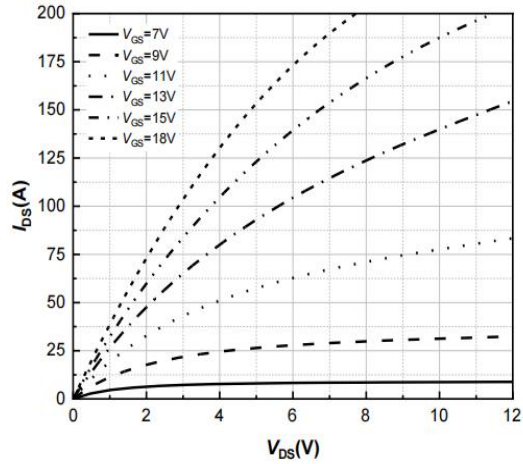


Figure 2. Output Characteristics  
 $T_j = 25^\circ\text{C}$

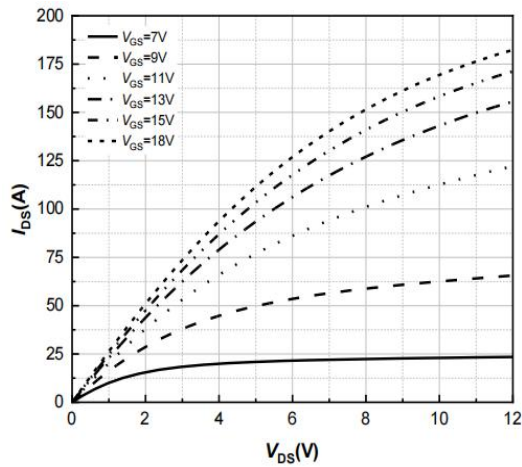


Figure 3. Output Characteristics  
 $T_j = 175^\circ\text{C}$

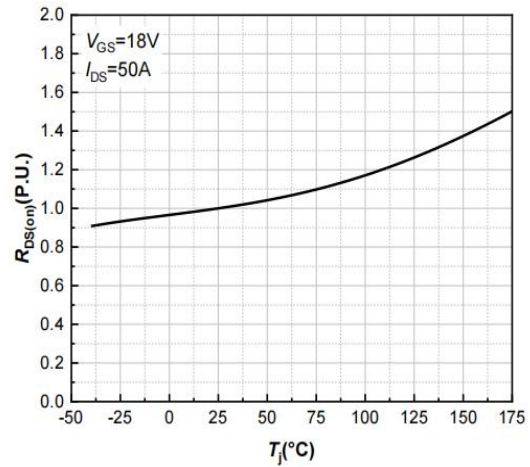


Figure 4. Normalized On-Resistance vs. Temperature

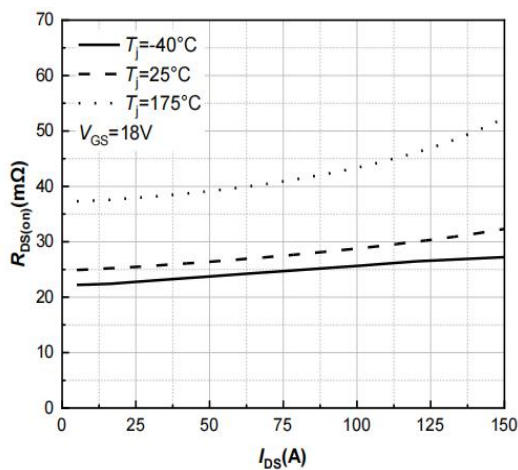


Figure 5. On-Resistance vs. Drain Current  
For Various Temperatures

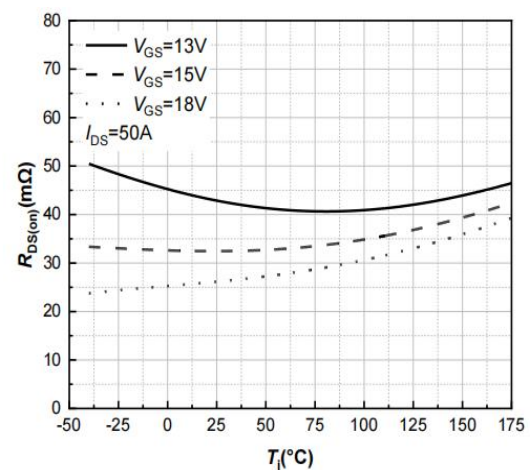


Figure 6. On-Resistance vs. Temperature  
For Various Gate Voltage

### RATINGS AND CHARACTERISTIC CURVES

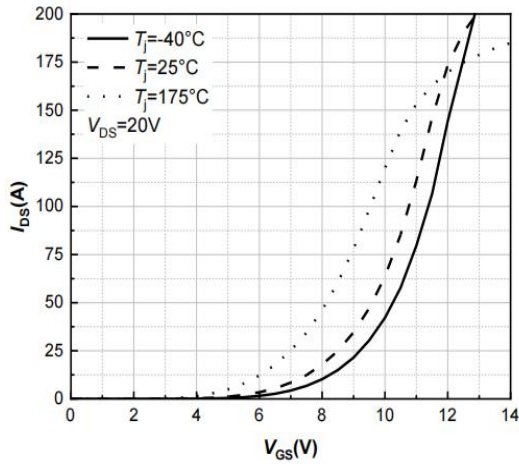


Figure 7. Transfer Characteristic for Various Junction Temperatures  
 $V_{DS}=20V$

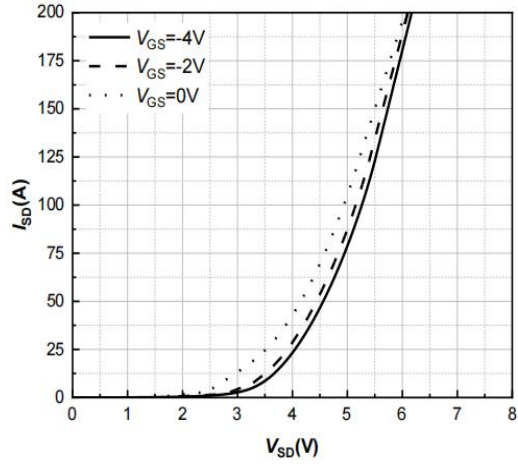


Figure 8. Body Diode Characteristic  
 $T_J=40^{\circ}C$

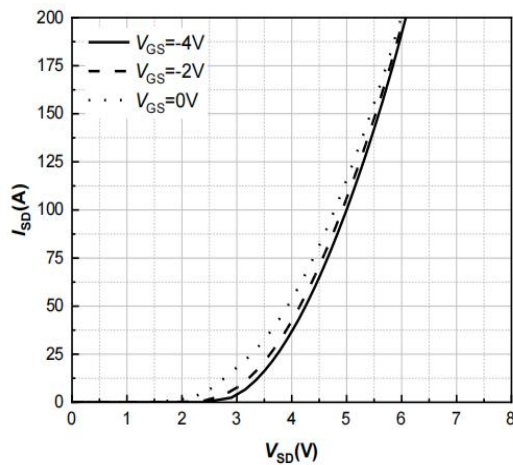


Figure 9. Body Diode Characteristic  
 $T_J=25^{\circ}C$

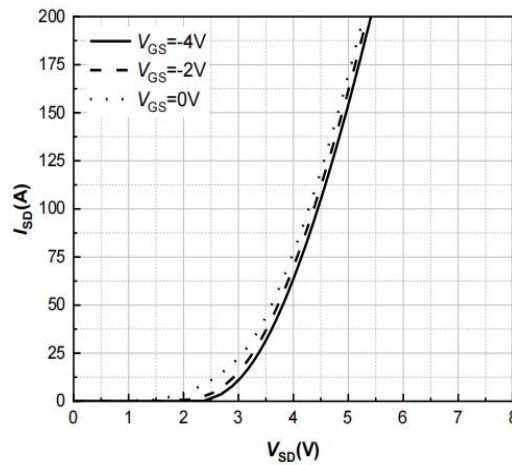


Figure 10. Body Diode Characteristic  
 $T_J=175^{\circ}C$

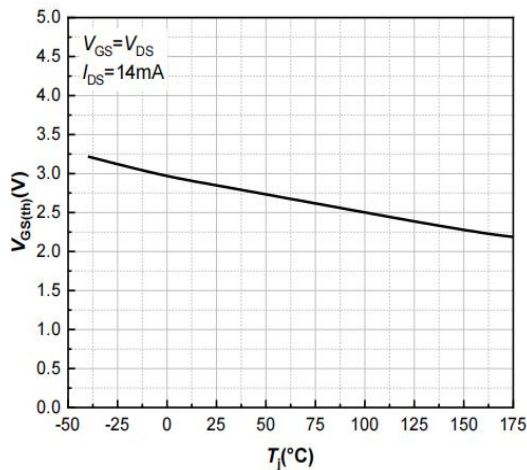


Figure 11. Threshold Voltage vs. Temperature

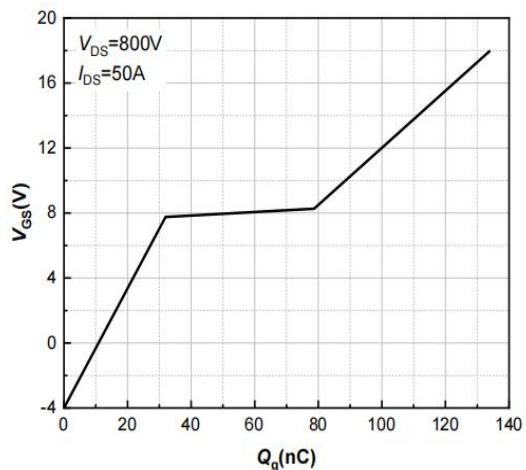


Figure 12. Gate Charge Characteristics

## RATINGS AND CHARACTERISTIC CURVES

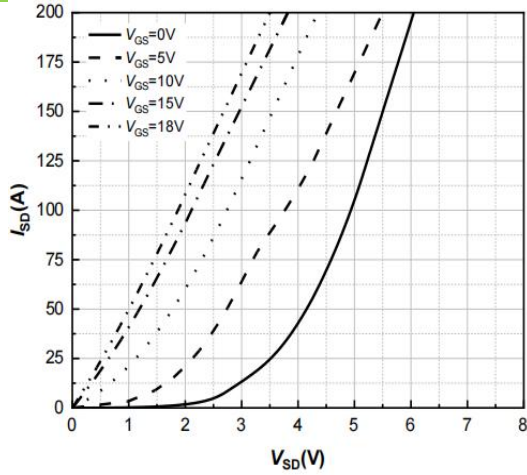


Figure 13. 3rd Quadrant Characteristic  
 $T_j = -40^\circ\text{C}$

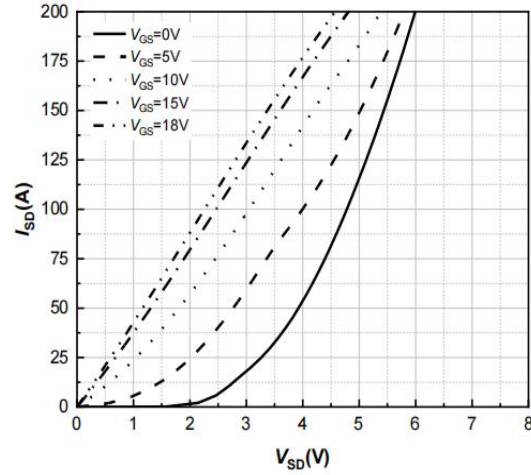


Figure 14. 3rd Quadrant Characteristic  
 $T_j = 25^\circ\text{C}$

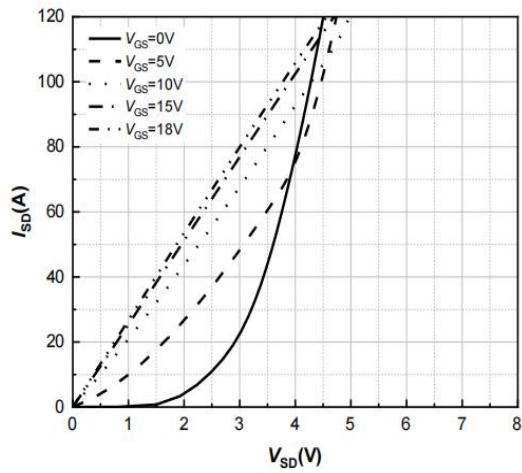


Figure 15. 3rd Quadrant Characteristic  
 $T_j = 175^\circ\text{C}$

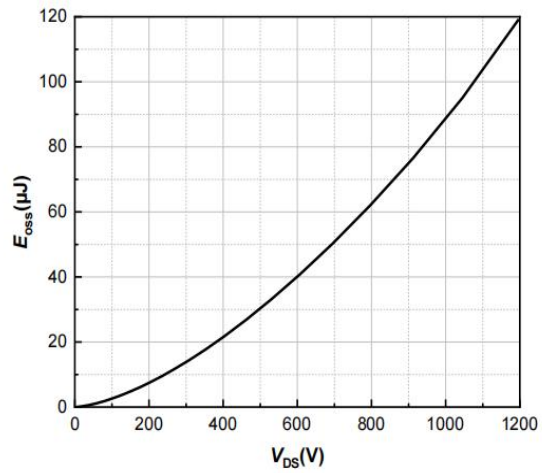


Figure 16. Output Capacitor Stored Energy

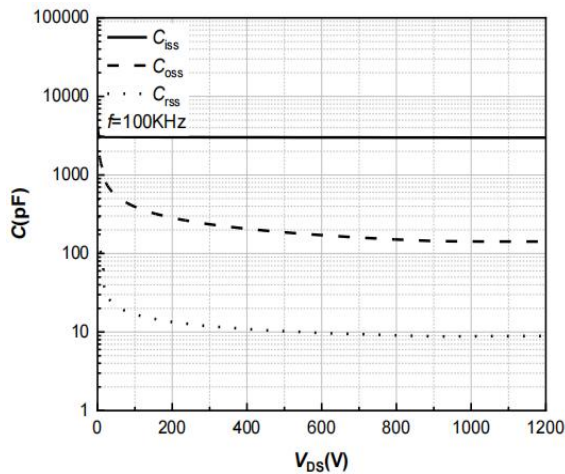
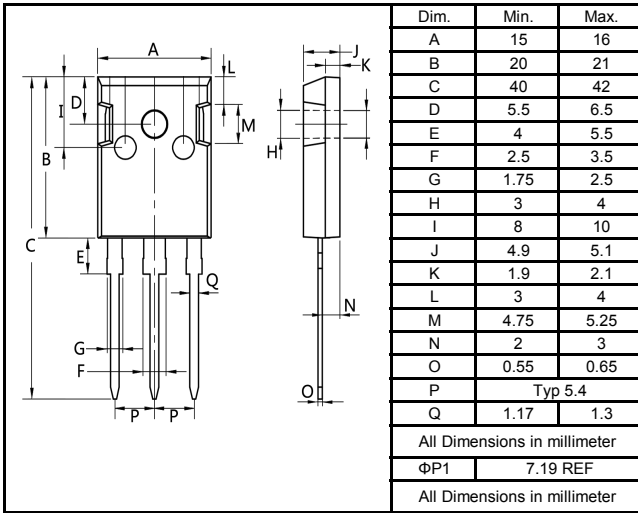


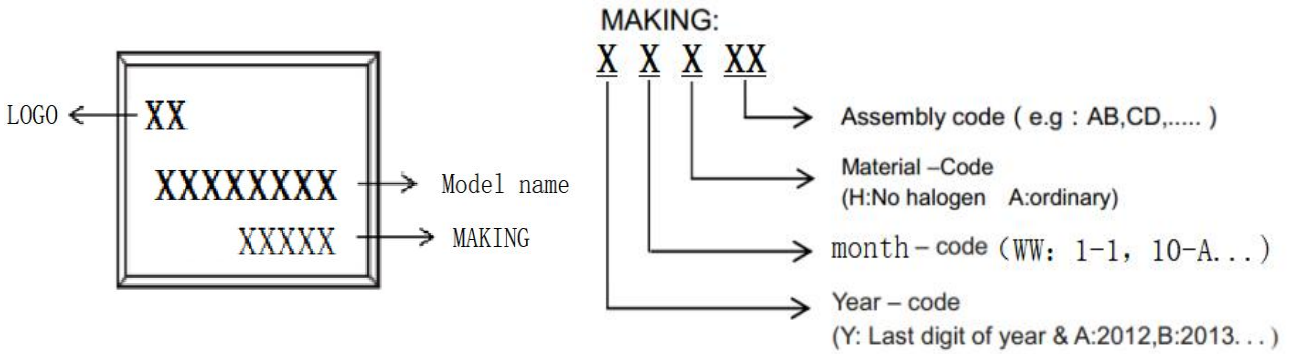
Figure 17. Capacitances vs. Drain-Source

### Package Outline Dimensions millimeters

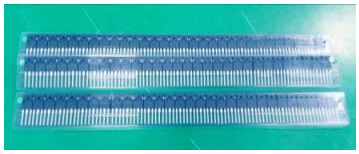


T0-247



### Marking on the body



### Packing instruction

PKG	Minimal Package	Box	Carton
TO-247			
	30pcs/pdpe	600pcs/box	3000pcs/Carton



# LSC030M120B

## SiC N-Channel MOSFET

### Notice

All product, product specifications and data are subject to change without notice to improve. The right to explain is owned by LINGXUN electronics company.

Confirm that operation temperature is within the specified range described in the product specification. Avoid applying poer exceeding normal rated

poer; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

LINGXUN electronics shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

<http://www.lxmicro.com>

### Revision History

Rev	Changes	Date
1.0	First version	2025/10/9